Zener Diode

DZ2S62000L

Panasonic

DZ2S62000L

Silicon epitaxial planar type

For ESD protection

■ Features

- High ESD
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: TG

■ Packaging

Embossed type (Thermo-compression sealing) 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

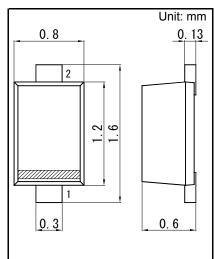
Parameter	Symbol	Rating	Unit
Total power dissipation *1	PT	150	mW
Electrostatic discharge *2	ESD	±8	kV
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note) *1 Mounted on glass epoxy print board. (45 mm x 45 mm x 1 mm) Soldering size : 0.8 x 0.6 mm

Soldering Size . 0.0 x 0.0 min

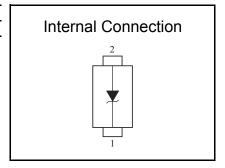
*2 Test method:IEC61000_4_2

(C = 150 pF , R = 330 Ω , Contact and Air discharge : 10 times)



- 1. Cathode
- 2. Anode

Panasonic	SSMini2-F5-B
JEITA	SC-79
Code	SOD-523



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■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Zener voltage *1, *2	VZ	IZ = 2 mA	58.0	62.0	66.0	V
Reverse current	IR	VR = 47 V			0.05	μΑ
Terminal capacitance	Ct	VR = 0 V, f = 1 MHz		14		pF
Temperature coefficient of zener voltage *3	SZ	IZ = 2 mA		43.0		mV/°C

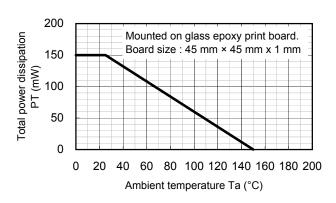
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
 - 2. Absolute frequency of input and output is 5 MHz.
 - 3. *1 The temperature must be controlled 25 °C for VZ mesurement. VZ value measured at other temperature must be adjusted to VZ (25 °C)
 - *2 VZ guaranteed 20 ms after current flow.
 - *3 Tj = 25 °C to 150 °C

Zener Diode

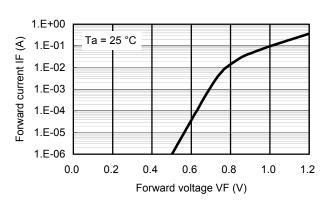
DZ2S62000L

Technical Data (reference)

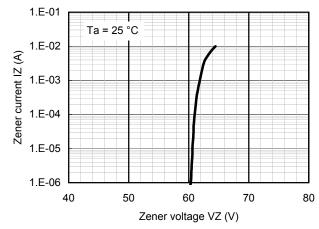
PT - Ta



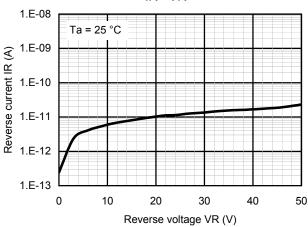
IF - VF



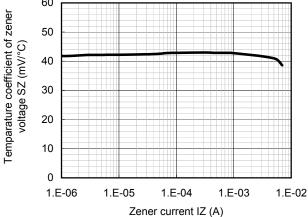
IZ - VZ



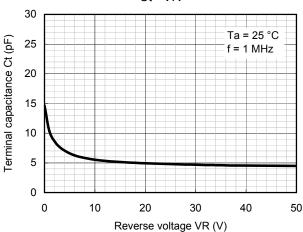
IR - VR



SZ - IZ



Ct - VR



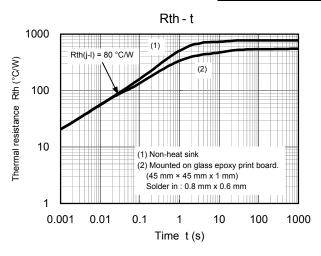
Doc No. TT4-EA-14825 Revision. 1

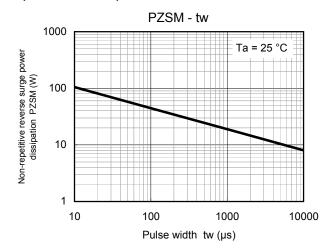
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Technical Data (reference)





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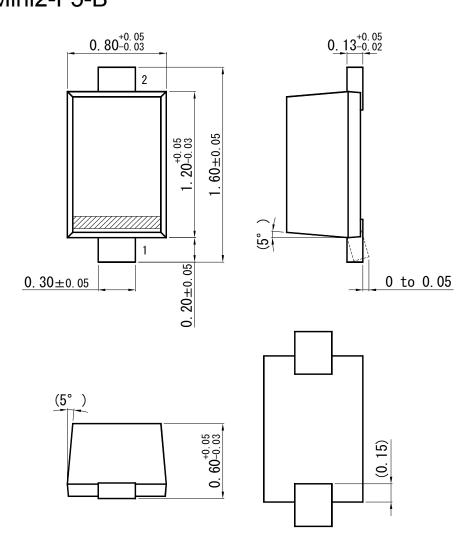
Zener Diode

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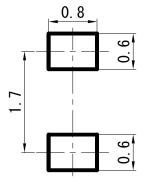
SSMini2-F5-B

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Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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